

INTERNATIONAL RECTIFIER



REPETITIVE AVALANCHE RATED AND dv/dt RATED

HEXFET[®] TRANSISTOR

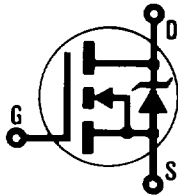
IRFM350

2N7227

JANTX2N7227

JANTXV2N7227

[REF: MIL-S-19500/592]



N-CHANNEL

400 Volt, 0.315 Ohm HEXFET

The HEXFET[®] technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance.

The HEXFET transistors also feature all of the well established advantages of MOSFETs such as voltage control, very fast switching, ease of paralleling and temperature stability of the electrical parameters.

They are well suited for applications such as switching power supplies and virtually any application where military and/or high reliability is required.

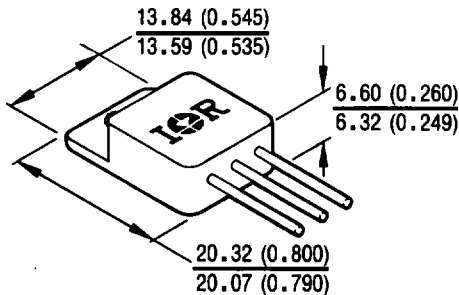
Product Summary

Part Number	V_{DSS}	$R_{DS(on)}$	I_D
IRFM350	400V	0.315 Ω	14A

FEATURES:

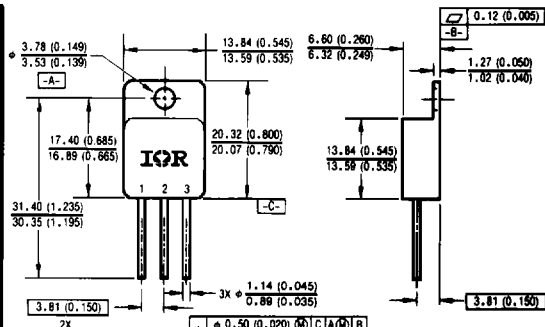
- Repetitive Avalanche Rating
- Isolated and Hermetically Sealed
- Alternative to TO-3 Package
- Simple Drive Requirements
- Ease of Paralleling
- Ceramic Eyelets

CASE STYLE AND DIMENSIONS



CAUTION

BERYLLIA WARNING PER MIL-S-19500
SEE PAGE I-340



LEGEND

- 1 DRAIN
- 2 SOURCE
- 3 GATE

NOTES

- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M - 1982
- 2 ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES)

Conforms to JEDEC Outline TO-254AA*
Dimensions in Millimeters and (Inches)

*For leadform configurations see page I-340, fig. 15



Absolute Maximum Ratings


Parameter	IRFM350, JANTXV-, JANTX-, 2N7227	Units
I_D @ $V_{GS} = 10V, T_C = 25^\circ C$	Continuous Drain Current	14
I_D @ $V_{GS} = 10V, T_C = 100^\circ C$	Continuous Drain Current	9.0
I_{DM}	Pulsed Drain Current ①	56
P_D @ $T_C = 25^\circ C$	Max. Power Dissipation	150
	Linear Derating Factor	1.2
V_{GS}	Gate-to-Source Voltage	± 20
EAS	Single Pulse Avalanche Energy ②	700 (See Fig. 12)
I_{AR}	Avalanche Current ①	14 (See E_{AR})
EAR	Repetitive Avalanche Energy ①	15 (See Fig. 13)
dv/dt	Peak Diode Recovery dv/dt ③	4.0 (See Fig. 13)
T_J	Operating Junction	-55 to 150
T_{STG}	Storage Temperature Range	
	Lead Temperature	300 (0.063 in. (1.6 mm) from case for 10s)
	Weight	9.3 (typical)

Electrical Characteristics @ $T_J = 25^\circ C$ (Unless Otherwise Specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions	
BV_{DSS}	Drain-to-Source Breakdown Voltage	400	—	—	V	$V_{GS} = 0V, I_D = 1.0 \text{ mA}$
$\Delta BV_{DSS}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.46	—	V/ $^\circ C$	Reference to $25^\circ C, I_D = 1.0 \text{ mA}$
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance	—	—	0.315	Ω	$V_{GS} = 10V, I_D = 9.0A$ ④
		—	—	0.415		$V_{GS} = 10V, I_D = 14A$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
g_{fs}	Forward Transconductance	6.0	—	—	S (⑧)	$V_{DS} \geq 15V, I_{DS} = 9.0A$ ④
I_{DSS}	Zero Gate Voltage Drain Current	—	—	25	μA	$V_{DS} = 0.8 \times \text{Max. Rating}, V_{GS} = 0V$
		—	—	250		$V_{DS} = 0.8 \times \text{Max. Rating}$ $V_{GS} = 0V, T_J = 125^\circ C$
I_{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20V$
I_{GSS}	Gate-to-Source Leakage Reverse	—	—	-100		$V_{GS} = -20V$
Q_g	Total Gate Charge	52	—	110	nC	$V_{GS} = 10V, I_D = 14A$
Q_{gs}	Gate-to-Source Charge	5.0	—	18		$V_{DS} = 0.5 \times \text{Max. Rating}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	25	—	65		See Fig. 6 and 14
$t_{d(on)}$	Turn-On Delay Time	—	—	35	ns	$V_{DD} = 200V, I_D = 14A, R_G = 2.35\Omega$
t_r	Rise Time	—	—	190		See Fig. 11
$t_{d(off)}$	Turn-Off Delay Time	—	—	170		
t_f	Fall Time	—	—	130		
L_D	Internal Drain Inductance	—	8.7	—	nH	Measured from the drain lead, 6 mm (0.25 in.) from package to center of die.
L_S	Internal Source Inductance	—	8.7	—		Measured from the source lead, 6 mm (0.25 in.) from package to source bonding pad.
C_{iss}	Input Capacitance	—	2600	—	pF	$V_{GS} = 0V, V_{DS} = 25V$ $f = 1.0 \text{ MHz}$ See Fig. 5
C_{oss}	Output Capacitance	—	660	—		
C_{rss}	Reverse Transfer Capacitance	—	250	—		
C_{DC}	Drain-to-Case Capacitance	—	12	—		



Source-Drain Diode Ratings and Characteristics

Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S Continuous Source Current (Body Diode)	—	—	14	A	Modified MOSFET symbol showing the integral Reverse p-n junction rectifier. 
I_{SM} Pulsed Source Current (Body Diode) ①	—	—	56		
V_{SD} Diode Forward Voltage	—	—	1.7	V	$T_J = 25^\circ\text{C}$, $I_S = 14\text{A}$, $V_{GS} = 0\text{V}$ ④
t_{rr} Reverse Recovery Time	—	—	1200	nS	$T_J = 25^\circ\text{C}$, $I_F = 14\text{A}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$ ④
Q_{RR} Reverse Recovery Charge	—	—	11	μC	$V_{DD} \leq 50\text{V}$
t_{on} Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

Thermal Resistance

Parameter	Min.	Typ.	Max.	Units	Test Conditions
R_{thJC} Junction-to-Case	—	—	0.83	K/W ⑤	
R_{thCS} Case-to-Sink	—	0.21	—		Mounting surface flat, smooth, and greased
R_{thJA} Junction-to-Ambient	—	—	48		Typical socket mount

① Repetitive Rating; Pulse width limited by maximum junction temperature (see figure 9) Refer to current HEXFET reliability report

② @ $V_{DD} = 50\text{V}$, Starting $T_J = 25^\circ\text{C}$, $L \geq 6.3 \text{ mH}$, $R_G = 25\Omega$, Peak $I_L = 14\text{A}$

③ $I_{SD} \leq 14\text{A}$, $di/dt \leq 145 \text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^\circ\text{C}$ Suggested $R_G = 2.35\Omega$

④ Pulse width $\leq 300 \mu\text{s}$; Duty Cycle $\leq 2\%$

⑤ $K/W = ^\circ\text{C}/\text{W}$
 $W/K = \text{W}/^\circ\text{C}$

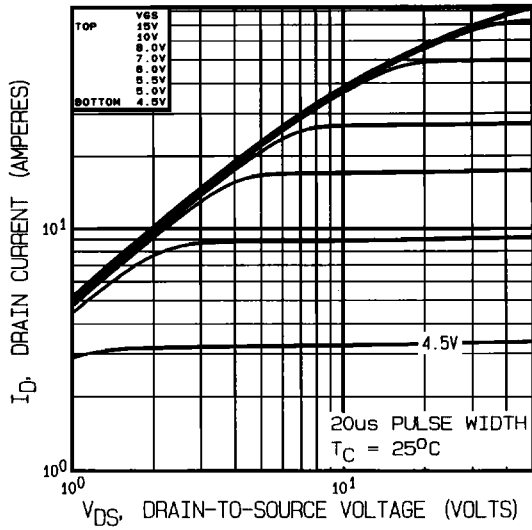


Fig. 1 — Typical Output Characteristics, $T_C = 25^\circ\text{C}$

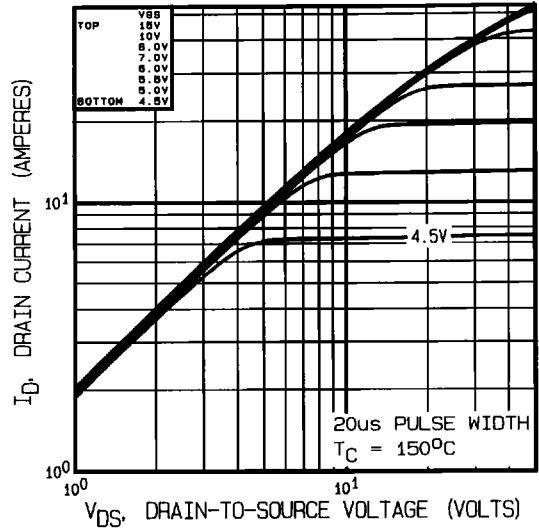


Fig. 2 — Typical Output Characteristics, $T_C = 150^\circ\text{C}$

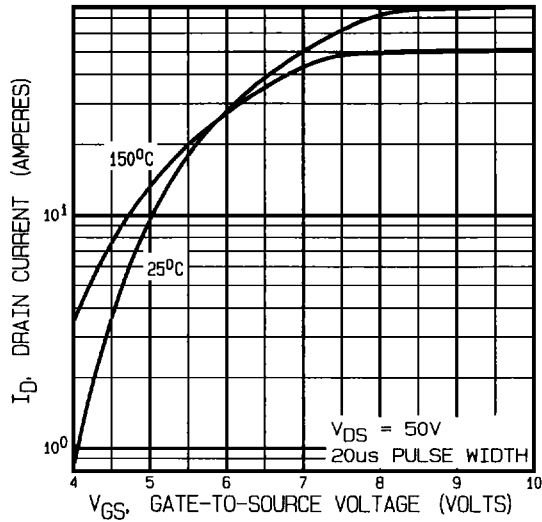


Fig. 3 — Typical Transfer Characteristics

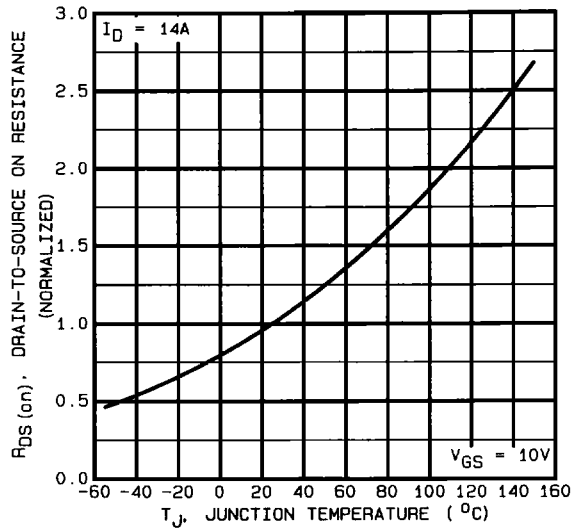


Fig. 4 — Normalized On-Resistance Vs. Temperature

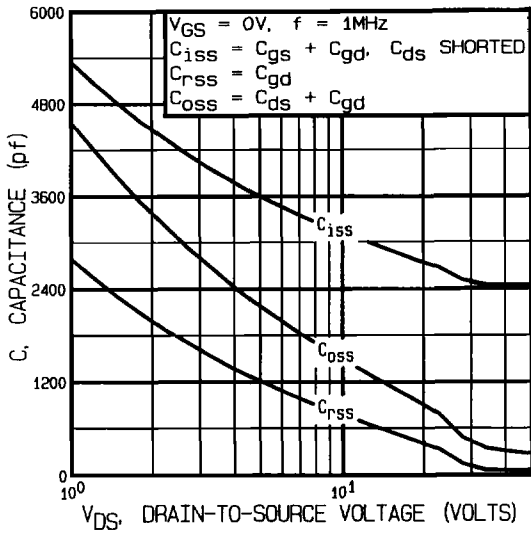


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

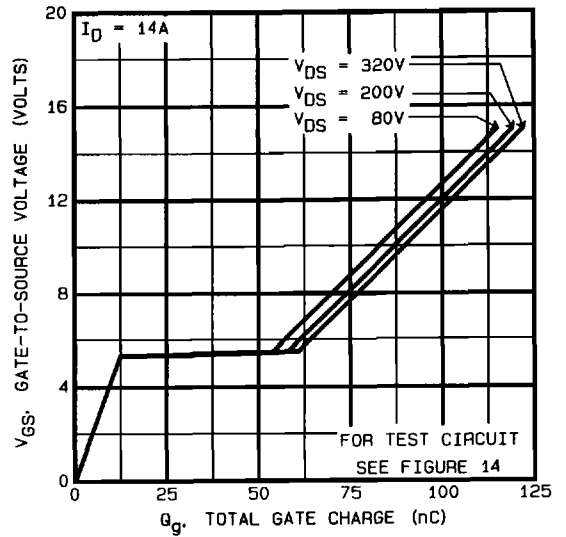


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

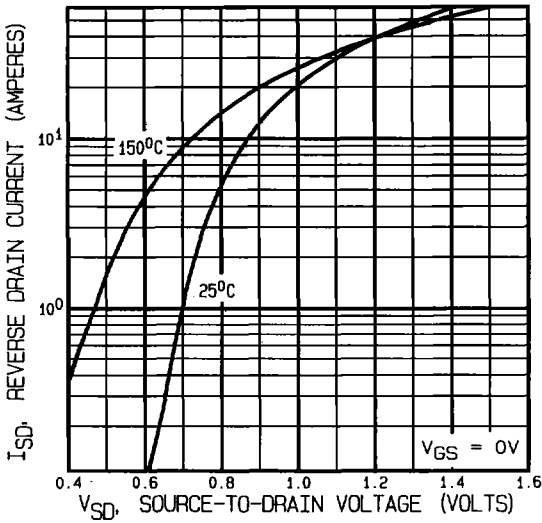


Fig. 7 — Typical Source-Drain Diode Forward Voltage

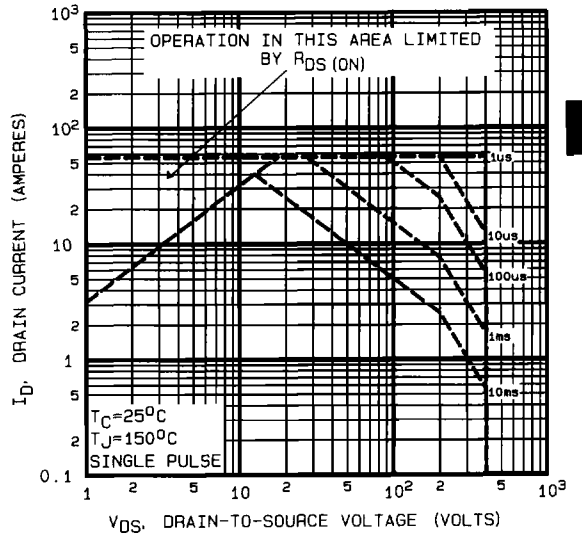


Fig. 8 — Maximum Safe Operating Area

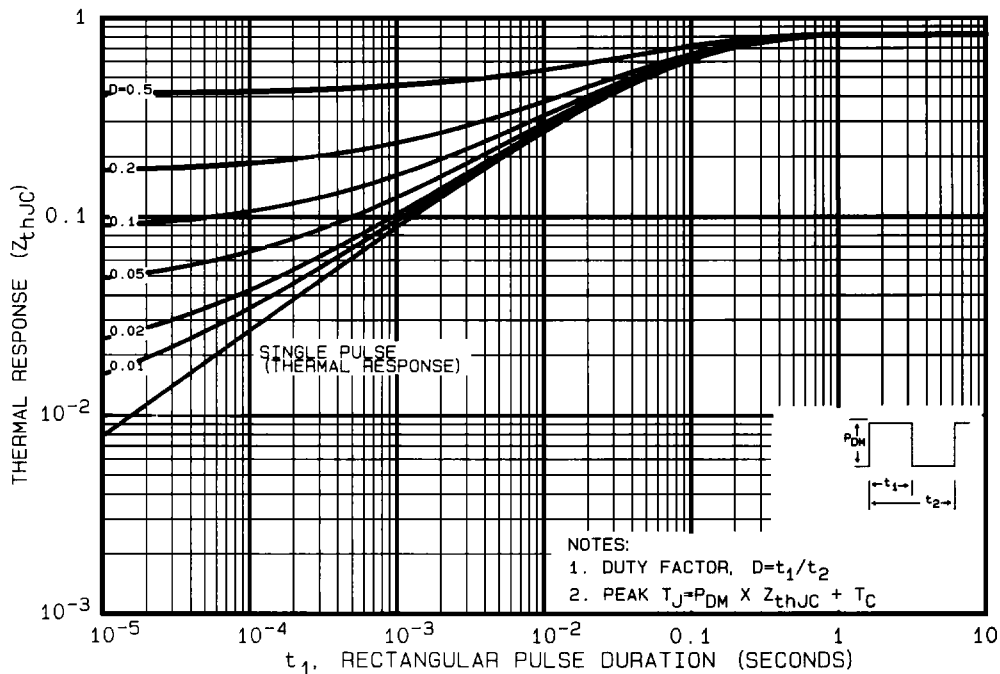


Fig. 9 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

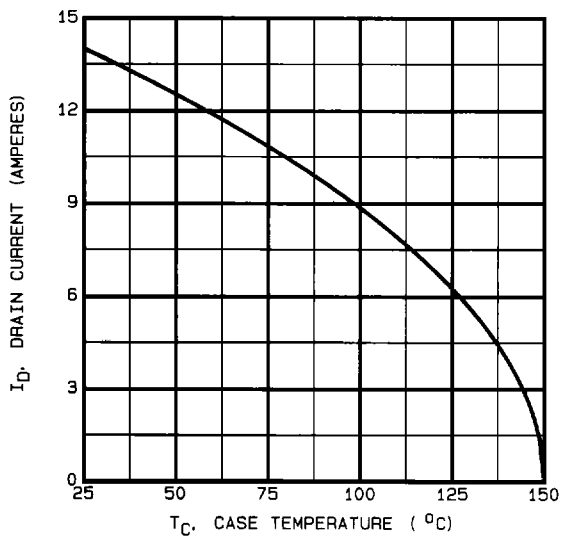


Fig. 10 — Maximum Drain Current Vs. Case Temperature

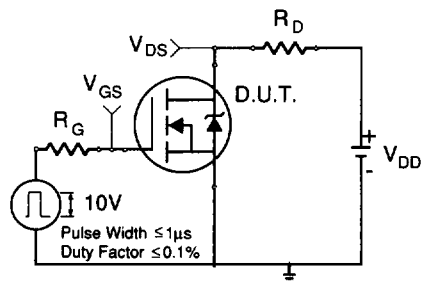


Fig. 11a — Switching Time Test Circuit

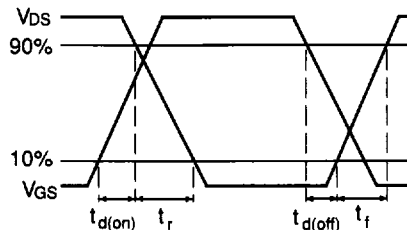


Fig. 11b — Switching Time Waveforms

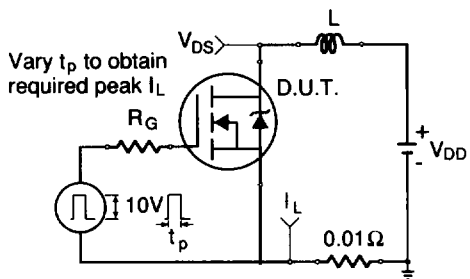


Fig. 12a — Unclamped Inductive Test Circuit

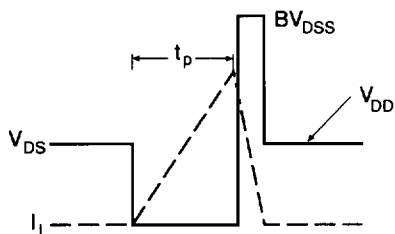


Fig. 12b — Unclamped Inductive Waveforms

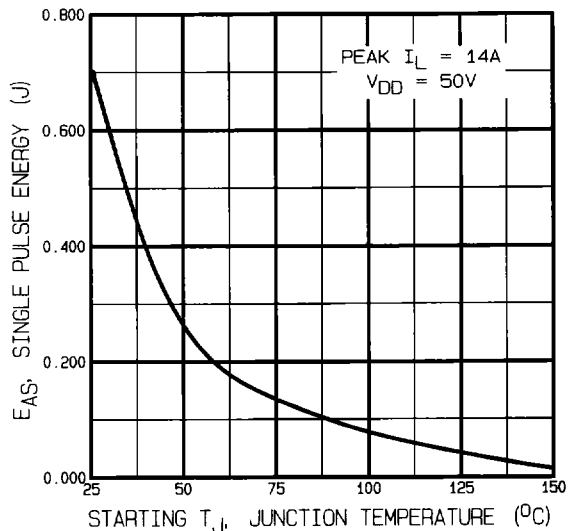


Fig. 12c — Maximum Avalanche Energy Vs. Starting Junction Temperature

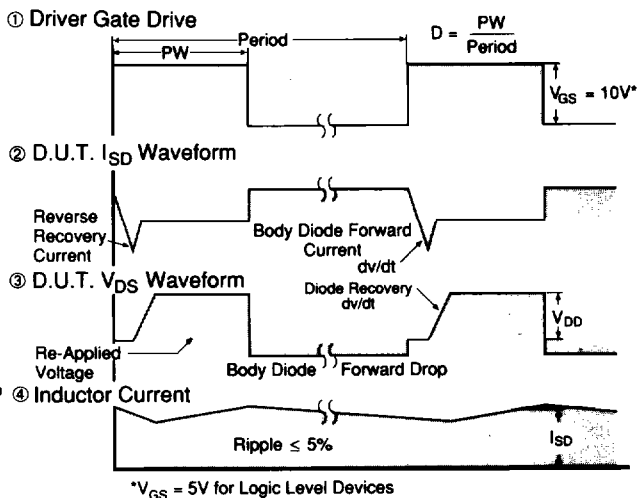
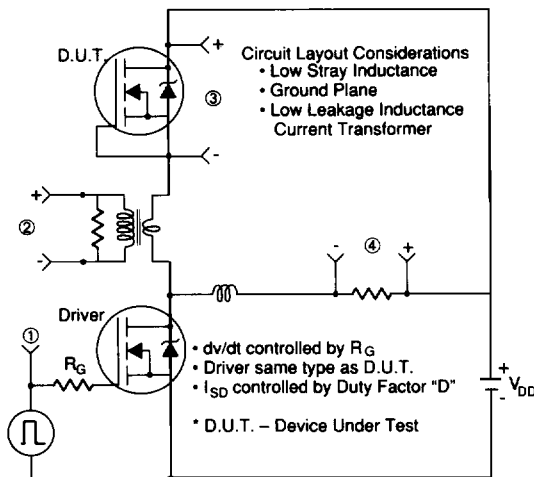


Fig. 13 — Peak Diode Recovery dv/dt Test Circuit

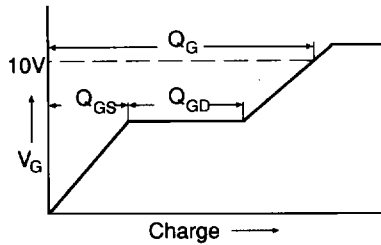


Fig. 14a — Basic Gate Charge Waveform

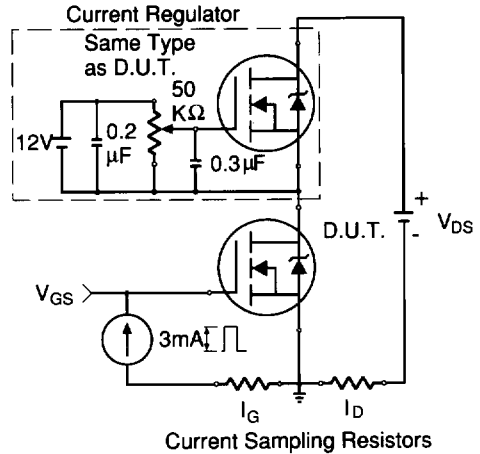


Fig. 14b — Gate Charge Test Circuit

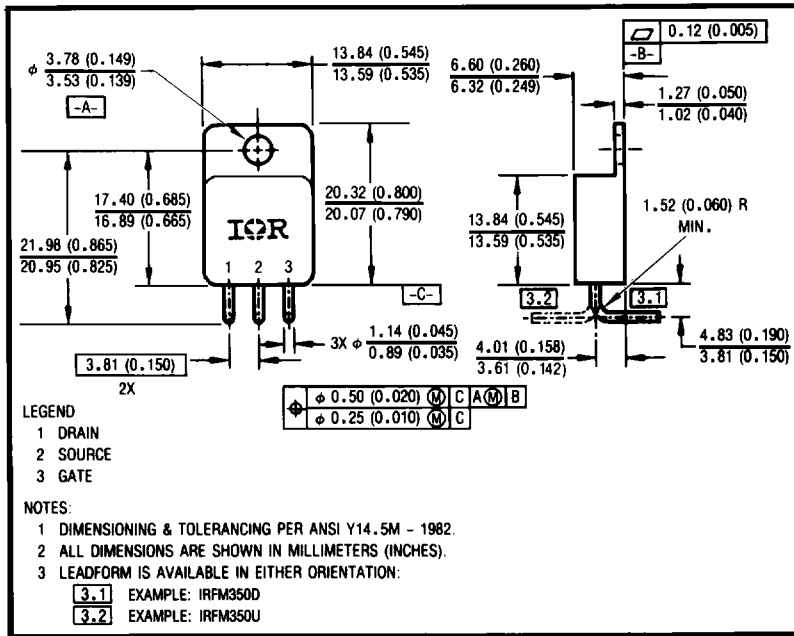


Fig. 15 — Optional Leadforms for Outline TO-254

BERYLLIA WARNING PER MIL-S-19500

Packages containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.